

IN THE CLAIMS:

1. (Canceled) Please cancel Claim 1.
2. (Canceled) Please cancel Claim 2.
3. (Canceled) Please cancel Claim 3.
4. (Canceled) Please cancel Claim 4.
5. (Canceled) Please cancel Claim 5.
6. (Original) A polishing method for polishing a metal film formed on a wafer surface having concave and convex patterns so as to fill concave portions on said wafer surface, comprising:
a step of polishing said metal film by alternating an electropolishing with a chemical mechanical polishing or chemical buffing.
7. (Original) The polishing method according to claim 6, wherein said electropolishing is conducted to roughen said metal film surface, and said chemical mechanical polishing or chemical buffing is conducted to smoothen said metal film surface roughened by said electropolishing.
8. (Original) The polishing method according to claim 6, wherein the electropolishing end point in a last electropolishing process among a plurality of electropolishing processes is determined by a change of a current waveform resulting from electropolishing said metal film.
9. (Original) The polishing method according to claim 8, wherein said electropolishing end point is found by differentiation of said change of the current waveform.

10. (Canceled) Please cancel Claim 10.

11. (Canceled) Please cancel Claim 11.